THE REAL WORLD OF MIC PACKAGING

Panel Discussion, Sponsored by

MTT-6 Committee on MICs

F. J. Rosenbaum, Moderator
Washington University
St. Louis, Missouri

Keynote Address: Microwave Integration--Promises and Problems, L. Young, M. L. Reuss, and B. E. Spielman, NRL, Washington, D. C.

Presentations by Panel Members:

Packaging L-band MIC Modules for Ground Based Applications, R. J. Taylor and P. S. Schaus, Westinghouse Defense and Space Center, Baltimore, Maryland

Impact Extruded MIC Packaging, J. Miley and K. Derdiarian, Microwave Associates, Burlington, Massachusetts

Thermal Expansion Problems in Hybrid Package Assembly, R. Jackson, IBM, Owego, New York

Microwave Planar Packages, D. Nelson, The Bendix Corporation, Sidney, New York

High Reliability Packages for Space Craft P. Petrelis, TRW, Redondo Beach, California